

ABSTRACT OF THE DISCLOSURE

This invention provides a light-emitting diode which permits mass production and dense packing into a pattern based on the use of a reflow furnace. Its reflection mirror 15 is obtained by stamping a metal plate to give it a smooth concave shape, and treating its concave surface by plating or depositing, for example, silver. The reflection mirror 15 is placed in an opposing relation to the light-emitting surface of a light-emitting element 11; is shaped like approximately a paraboloid of revolution; and has a focal point at which the center of the light emitting surface of light-emitting element 11 is disposed. The light-emitting element 11, parts of lead assemblies 12a and 12b, a bonding wire 13 and the reflection mirror 15 is integrally sealed with a light transmissible material 14 by transfer molding. The surface of the light transmissible material 14 at the rear of the light-emitting element serves as a radiation surface 21.

(Fig. 2)